HSB226S

Silicon Schottky Barrier Diode for High Speed Switching

REJ03G0591-0200
Rev.2.00
Sep 15, 2006

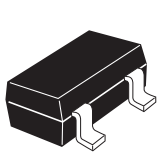
Features

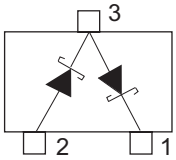
- Low reverse current, Low capacitance.
- CMPAK package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Name	Package Code
HSB226S	E7	CMPAK	PTSP0003ZB-A

Pin Arrangement





(Top View)

1. Cathode 2
2. Anode 1
3. Cathode 1
   Anode 2

Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Repetitive peak reverse voltage	V_{RRM}	25	V
Non-Repetitive peak forward surge current	I_{FSM} *1 *2	200	mA
Forward current	I_F *2	50	mA
Junction temperature	Tj	125	°C
Storage temperature	Tstg	–55 to +125	°C

Notes: 1. 10 ms sine wave 1 pulse
2. Two device total

Electrical Characteristics *

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	V_{F1}	—	—	0.33	V	I_F = 1 mA
	V_{F2}	—	—	0.38		I_F = 5 mA
Reverse current	I_R	—	—	450	nA	V_R = 20 V
Capacitance	C	—	—	2.80	pF	V_R = 1 V, f = 1 MHz

Note: Per one device

Main Characteristic

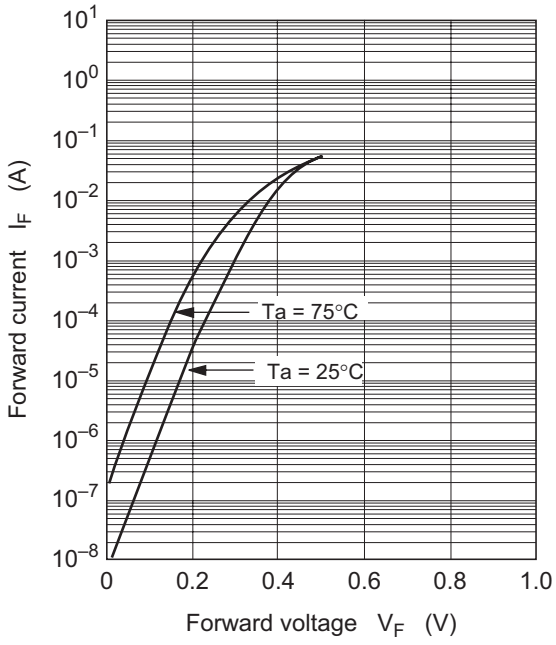


Fig.1 Forward current vs. Forward voltage

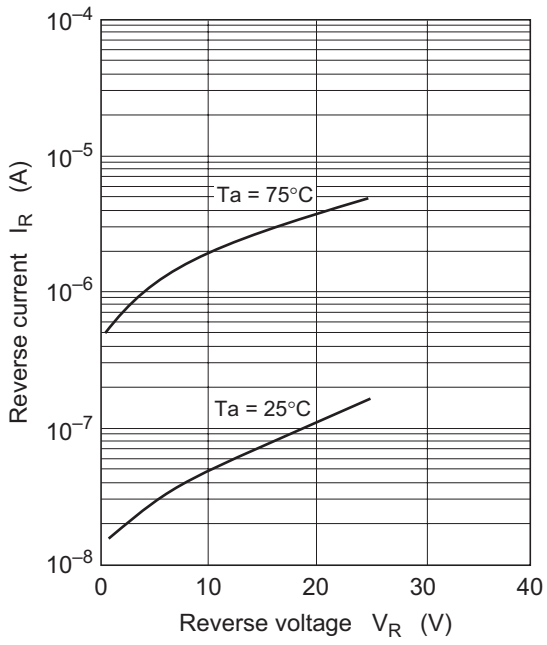


Fig.2 Reverse current vs. Reverse voltage

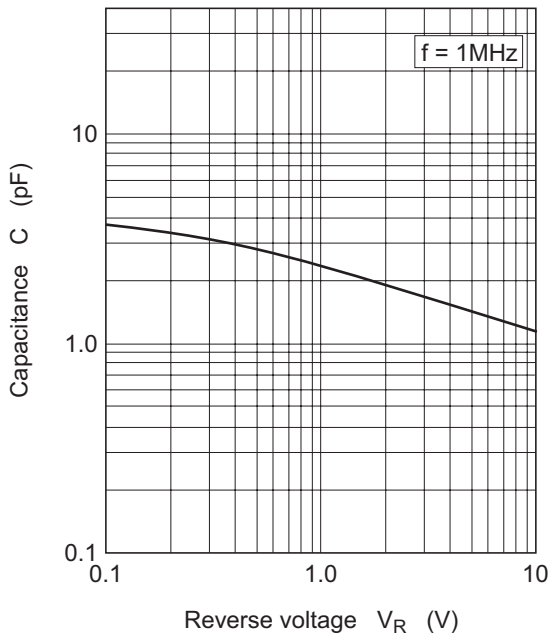
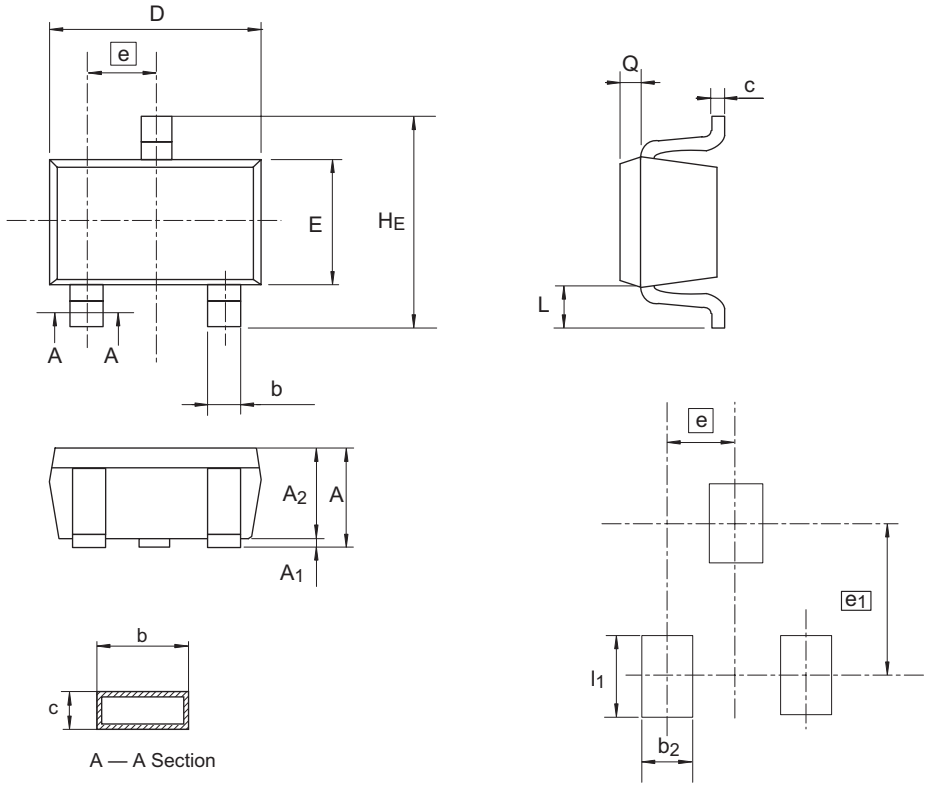


Fig.3 Capacitance vs. Reverse voltage

Package Dimensions

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
SC-70	PTSP0003ZB-A	CMPAK / CMPAKV	0.006g



Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
A	0.8	-	1.1
A_1	0	-	0.1
A_2	0.8	0.9	1.0
b	0.25	0.3	0.4
c	0.1	0.16	0.26
D	1.8	2.0	2.2
E	1.15	1.25	1.35
e	-	0.65	-
H_E	1.8	2.1	2.4
L	-	0.425	-
b_2	-	-	0.45
e_1	-	1.5	-
l_1	-	-	0.9
Q	-	0.2	-

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